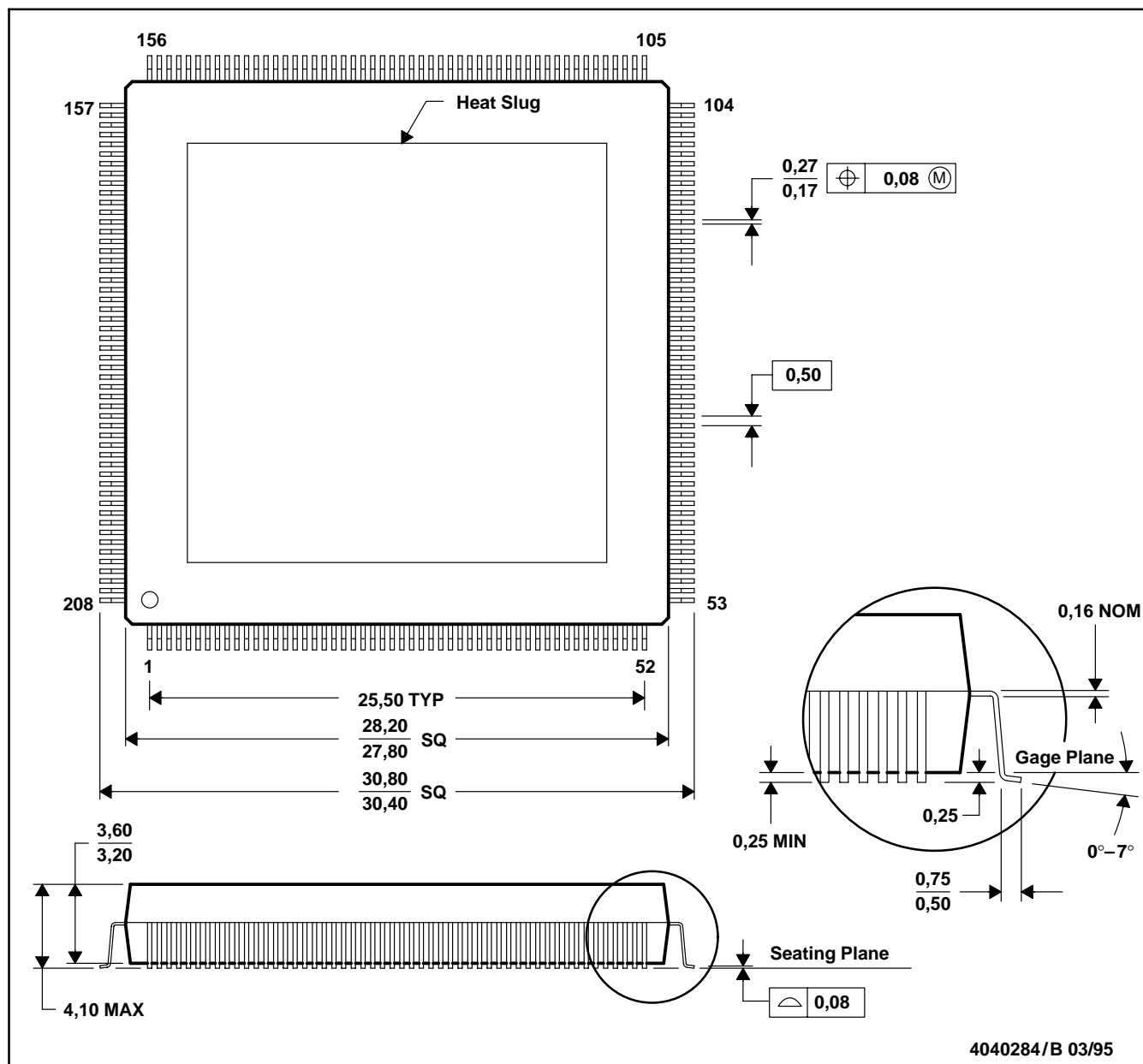


PPB (S-PQFP-G208)

PLASTIC QUAD FLATPACK (DIE-DOWN)



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Thermally enhanced molded plastic package with a heat slug (HSL)
 - Falls within JEDEC MO-143

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